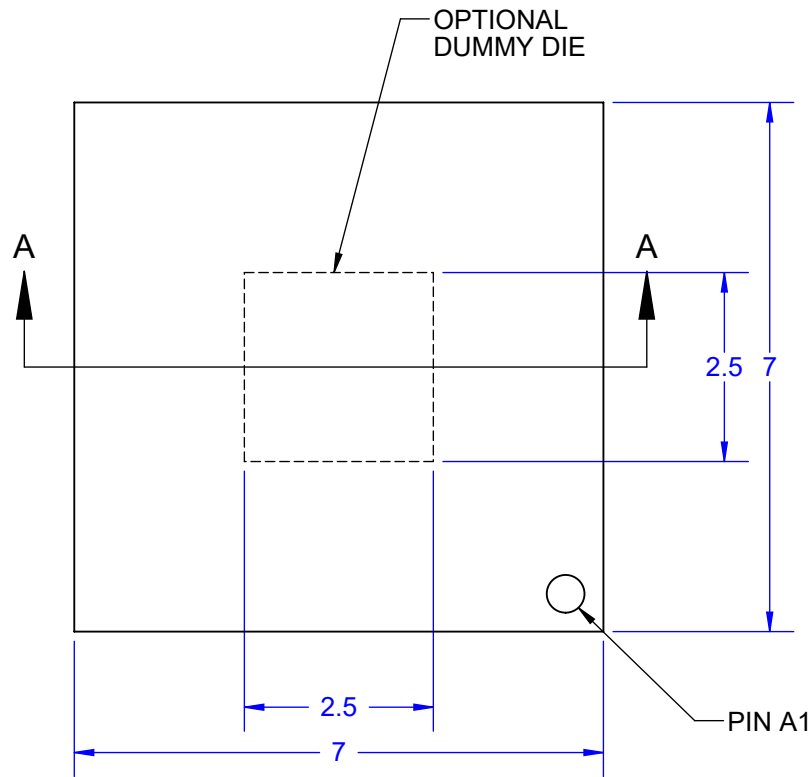
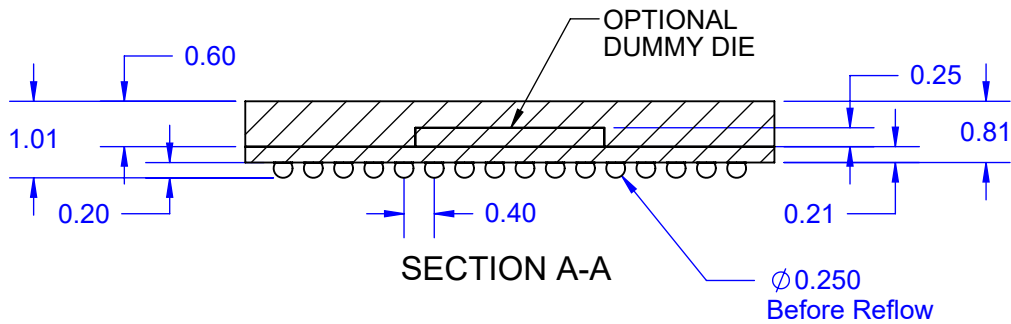
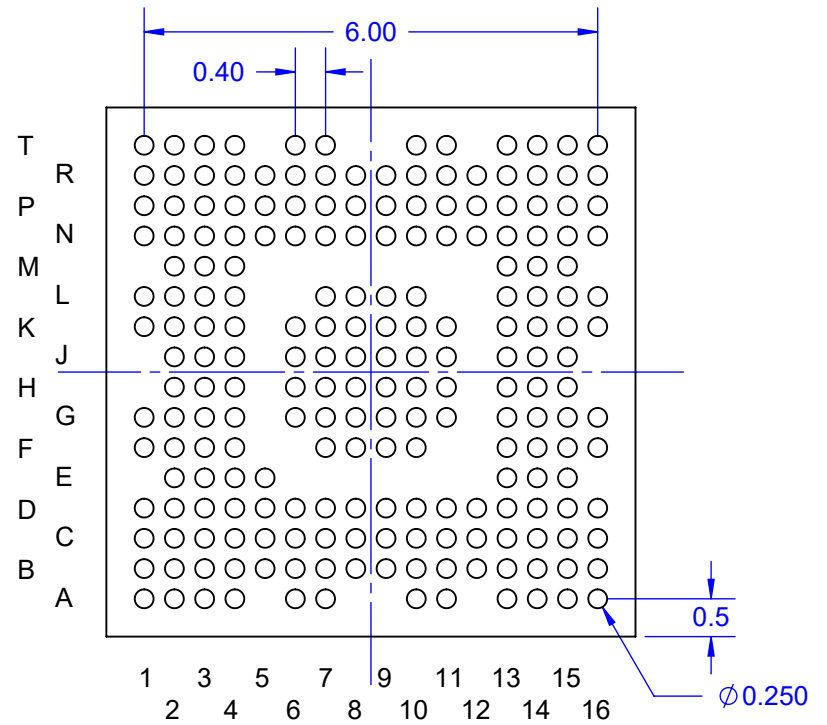


TOP VIEW



BALL VIEW



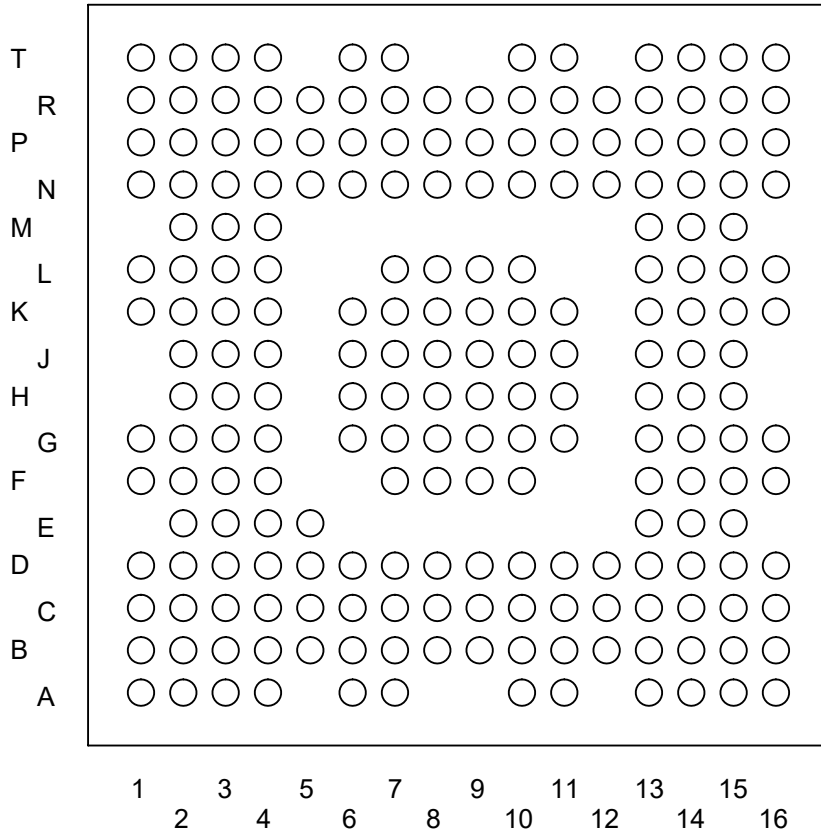
NOTES: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25MM.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.22MM (8.6mil).
- 5) PAD Cu DIAMETER: BT.
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

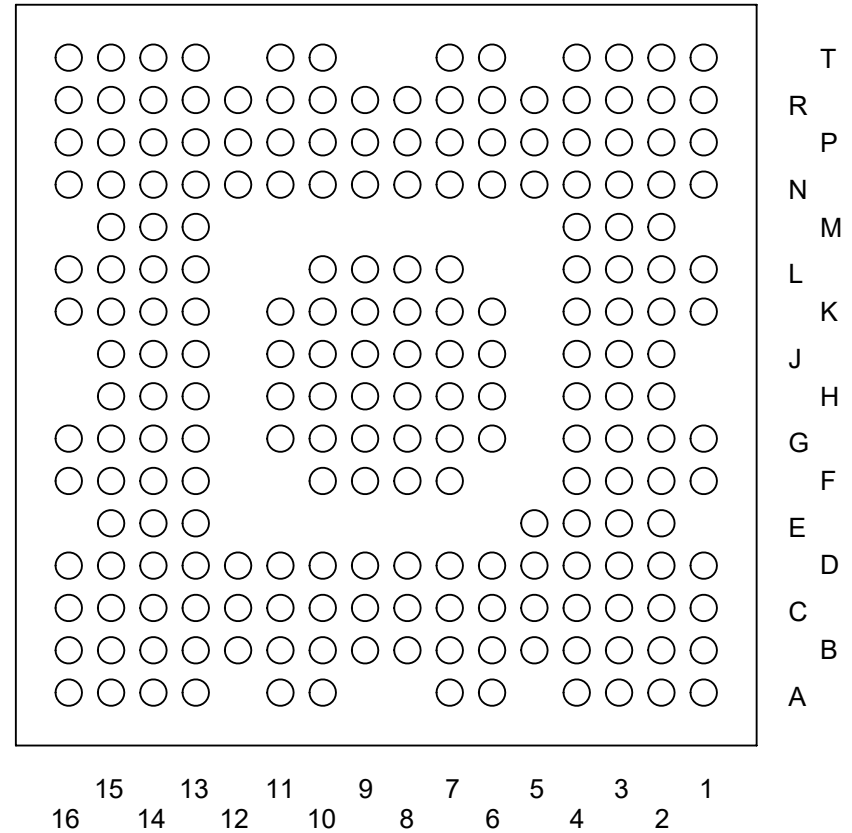
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA209T.4C-16x16-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

APPROVALS	DATE	TopLine®		
DRAWN T. Au	09/05/16			
ENG M. Hart	09/05/16	TITLE BGA209T.4C-16x16 DUMMY PART		
MFG		SCALE 10:1	SIZE A	DRAWING NO. 170181
QA				REV A
CUST				
REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 2

BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



NOTES: (Unless Otherwise Specified).

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.356mm (14 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.154mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.30mm (11.8 MIL).

APPROVALS	DATE	TopLine®			
DRAWN T. Au	09/05/16				
ENG M. Hart	09/05/16	TITLE BGA209T.4C-16x16 DUMMY PART			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		14:1	A	170181	A
CUST		DO NOT SCALE DRAWING			SHEET 2 OF 2
REVISED					